

SPECIFICATION AMENDMENTS

Please amend page 18 of the Specification containing the
Abstract as follows:

~~Method for manufacturing a housing for a chip having a
micromechanical structure~~

Abstract of the Disclosure:

A method for manufacturing a chip housing ~~for a chip having a
micromechanical structure is primarily based on~~ includes a
first basis ~~comprising~~ having a photolithographically
structurable layer on ~~at least one partial region of a main
face, . The same is structured in order to obtain into a
cover for the micromechanical structure. Further, a~~ A chip
has comprising the micromechanical structure is provided,
~~which is arranged at a main face of the chip between the
first contact elements. A second photolithographically
structurable layer is applied to at least one partial region
of the main face of the chip and is structured for generating
forming a recess in the same surrounded by a wall in the
region of~~ near the micromechanical structure and ~~for exposing
the first contact elements. After that~~ Then, the first basis
and the chip are merged ~~such that~~ with the micromechanical
structure and the cover ~~are facing~~ facing each other and are

aligned with each other, ~~so that~~ and the recess ~~is~~ closed by the cover. Removing the first basis leads to ~~a chip~~ ~~comprising~~ an on-chip cavity. Afterwards, a second basis and the chip are merged ~~such that the~~ with the first contact elements ~~are~~ connected to the second basis via a conductive structure. Afterwards, the second basis is removed for exposing the conductive structure. The method is less subject to ~~the~~ cost and size limitations of known housing technologies.